

2SK2590 Silicon N Channel MOS FET

REJ03G1021-0300 (Previous: ADE-208-1365A) Rev.3.00 Sep 07, 2005

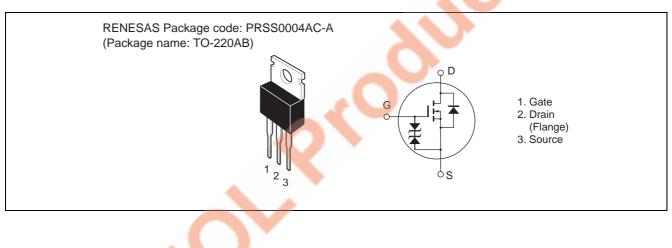
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator, DC-DC converter, motor control

Outline





Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	200	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	ID	7	A
Drain peak current	I _{D(pulse)} * ¹	28	А
Body to drain diode reverse drain current	I _{DR}	7	А
Channel dissipation	Pch* ²	50	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

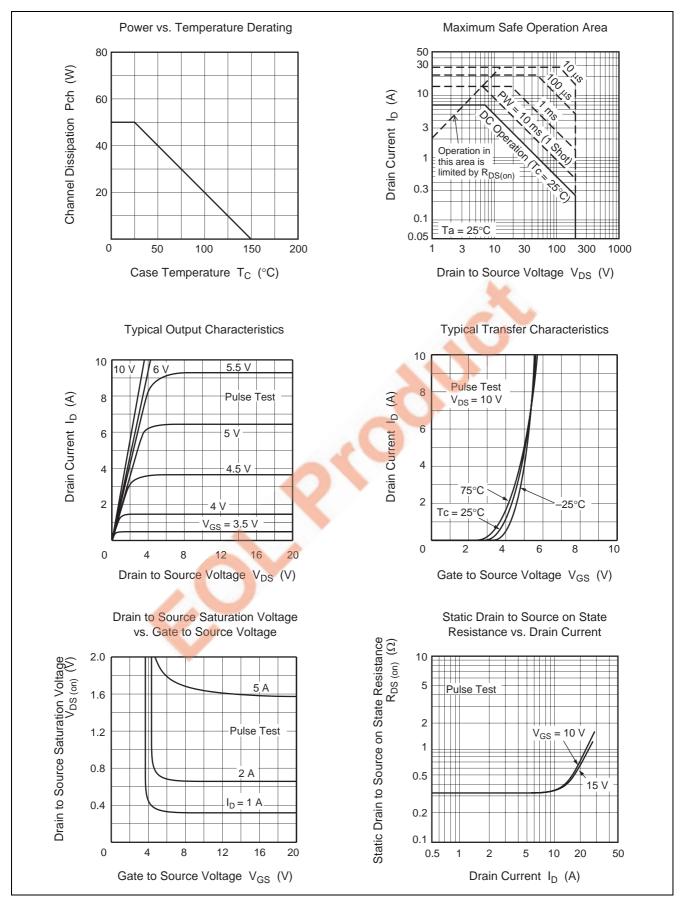
2. Value at $Tc = 25^{\circ}C$

Electrical Characteristics

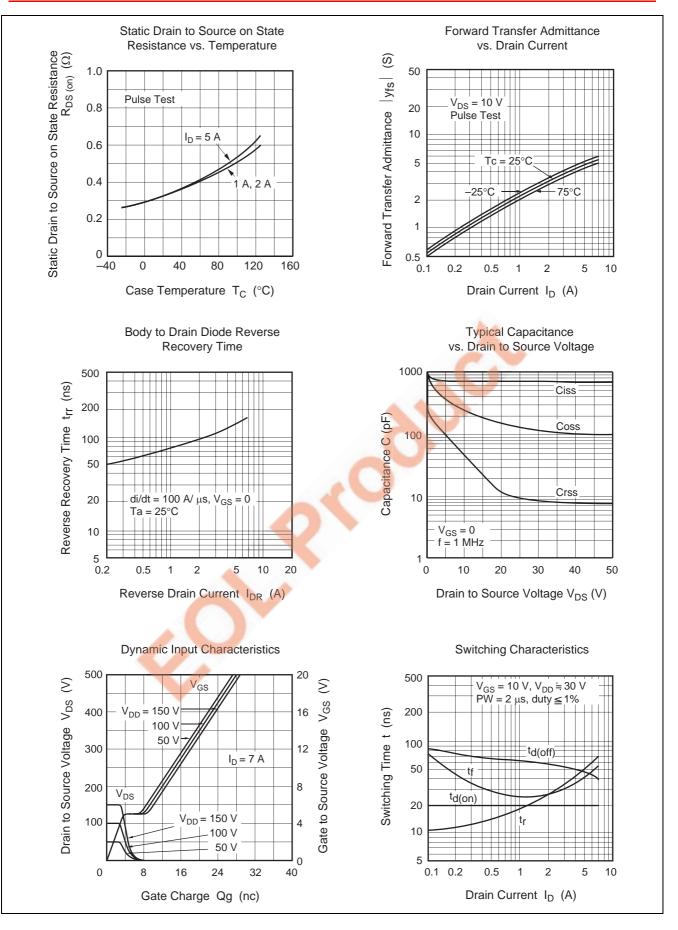
						(Ta = 25°C)
ltem	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR)DSS}	200	_	—	V	$I_{D} = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _{(BR)GSS}	±20	_	—	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}		-	±10	μA	$V_{GS} = \pm 16 \text{ V}, \text{ V}_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	—	250	μA	V_{DS} =160 V, V_{GS} = 0
Gate to source cutoff voltage	V _{GS(off)}	2.0	—	4.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state resistance	R _{DS(on)}	_	0.33	0.45	Ω	$I_D = 4 A, V_{GS} = 10 V^{*1}$
Forward transfer admittance	y _{fs}	3.0	4.5) -	S	$I_D = 4 \text{ A}, V_{DS} = 10 \text{ V}^{*1}$
Input capacitance	Ciss	_	700	_	pF	$V_{DS} = 10 V, V_{GS} = 0,$
Output capacitance	Coss	F	260	—	pF	f = 1 MHz
Reverse transfer capacitance	Crss	V	45	—	pF	
Turn-on delay time	t _{d(on)}		20	—	ns	$I_D = 4 \text{ A}, V_{GS} = 10 \text{ V},$ $R_L = 7.5 \Omega$
Rise time	tn	_	45	—	ns	
Turn-off delay time	t _{d(off)}		50	—	ns	
Fall time	tr	-	35	—	ns	
Body to drain diode forward voltage	VDF	_	1.1	—	V	$I_F = 7 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr} *	_	150	—	ns	I _F = 7 A, V _{GS} = 0, di _F / dt = 100 A / μs
Note: 3. Pulse Test						



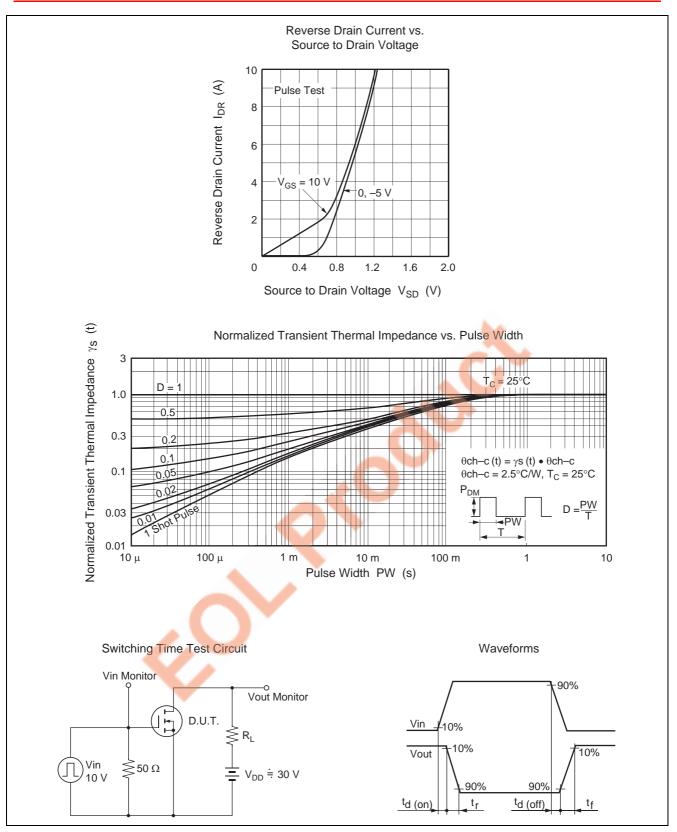
Main Characteristics



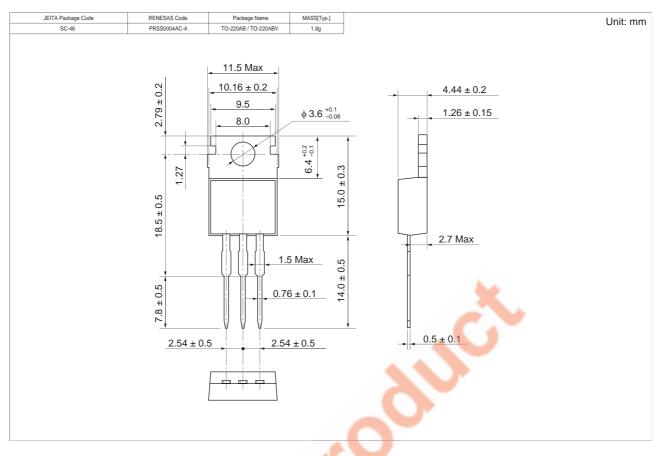








Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SK2590-E	500 pcs	Box (Sack)

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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Renesas Technology Malaysia Sdn. Bhd.

Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia Tel: <603> 7955-9390, Fax: <603> 7955-9510